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January 2014

NC7SZ125 TinyLogic[®] UHS Buffer with Three-State Output

Features

- Ultra-High Speed: t_{PD} 2.6 ns (Typical) into 50 pF at 5 V V_{CC}
- High Output Drive: ±24 mA at 3 V V_{CC}
- Broad V_{CC} Operating Range: 1.65 V to 5.5 V
- Matches Performance of LCX Operated at 3.3 V V_{CC}
- Power Down High-Impedance Inputs/Outputs
- Over-Voltage Tolerance Inputs Facilitate 5 V to 3 V Translation
- Proprietary Noise/EMI Reduction Circuitry
- Ultra-Small MicroPak™ Packages
- Space-Saving SOT23 and SC70 Packages

Description

The NC7SZ125 is a single buffer with three-state output from Fairchild's Ultra-High Speed (UHS) of TinyLogic $^{\otimes}$. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a very broad $V_{\rm CC}$ operating range. The device is specified to operate over the 1.65 V to 5.5 V range. The inputs and output are high impedance above ground when $V_{\rm CC}$ is 0 V. Inputs tolerate voltages up to 6 V independent of $V_{\rm CC}$ operating voltage. The output tolerates voltages above $V_{\rm CC}$ when in the 3-STATE condition.

Ordering Information

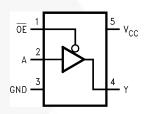
| Part Number | t Number Top Mark Package | | Packing Method |
|-------------|---------------------------|---|------------------------------|
| NC7SZ125M5X | 7Z25 | 5-Lead SOT23, JEDEC MO-178 1.6 mm | 3000 Units on Tape & Reel |
| NC7SZ125P5X | Z25 | 5-Lead SC70, EIAJ SC-88a, 1.25 mm Wide | 3000 Units on Tape & Reel |
| NC7SZ125L6X | DD | 6-Lead MicroPak™, 1.00 mm Wide | 5000 Units on Tape & Reel |
| NC7SZ125FHX | DD | 6-Lead, MicroPak2, 1x1 mm Body, .35mm Pitch | 5000 Units on Tape & Reel |

Connection Diagrams



Figure 1. Logic Symbol

Pin Configurations





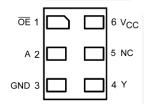


Figure 3. MicroPak™ (Top Through View)

Pin Definitions

| Pin # SC70 / SOT23 | Pin # MicroPak | Name | Description |
|--------------------|----------------|-----------------|----------------|
| 1 | 1 | OE | Input |
| 2 | 2 | A | Input |
| 3 | 3 | GND | Ground |
| 4 | 4 | Υ | Output |
| 5 | 6 | V _{CC} | Supply Voltage |
| \(\frac{1}{2}\) | 5 | NC | No Connect |

Function Table

| In | puts | Output |
|-----|------|--------|
| /OE | In A | Out Y |
| L | L | r r |
| L | Н | Н |
| Н | X | Z |

H = HIGH Logic Level

L = LOW Logic Level

X = HIGH or LOW Logic Level

Z = HIGH Impedance State

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | | | Min. | Max. | Unit | |
|-------------------------------------|--------------------------------------|------------------------|--|------|------|------|--|
| V _{CC} | Supply Voltage | | | -0.5 | 6.0 | V | |
| V _{IN} | DC Input Voltage | | | -0.5 | 6.0 | V | |
| V _{OUT} | DC Output Voltage | | | -0.5 | 6.0 | V | |
| | DC Input Diada Current | V _{IN} < -0.5 | 5 V | | -50 | mA | |
| I _{IK} | DC Input Diode Current | $V_{IN} > 6.0$ | V | | +20 | IIIA | |
| | DC Output Diada Current | V _{OUT} < -0 | .5 V | | -50 | mA | |
| I _{OK} | DC Output Diode Current | V _{OUT} > 6 | V _{OUT} > 6 V, V _{CC} =GND | | +20 | IIIA | |
| I _{OUT} | DC Output Current | DC Output Current | | (| ±50 | mA | |
| I _{CC} or I _{GND} | DC V _{CC} or Ground Current | | | | ±50 | mA | |
| T _{STG} | Storage Temperature Range | | | -65 | +150 | °C | |
| T_J | Junction Temperature Under Bia | IS | | | +150 | °C | |
| T_L | Junction Lead Temperature (Sol | dering, 10 Second | s) | | +260 | °C | |
| - /- | | SOT-23 | | | 200 | | |
| Б | Device Discipation at 19590 | SC70-5 | SC70-5 | | 150 | \/ | |
| P_D | Power Dissipation at +85°C | MicroPak | c-6 | | 130 | mW | |
| | | MicroPak | MicroPak2-6 | | 120 | | |
| ESD | Human Body Model, JESD22-A1 | 114 | | | 4000 | V | |
| ESD | Charged Device Model, JESD22 | -C101 | | | 2000 | V | |

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

| Symbol | Parameter | Conditions | Min. | Max. | Unit | |
|------------------|-------------------------------|--|------|-----------------|------|--|
| \/ | Supply Voltage Operating | | 1.65 | 5.50 | V | |
| V _{CC} | Supply Voltage Data Retention | | 1.50 | 5.50 | 7 v | |
| V _{IN} | Input Voltage | | 0 | 5.5 | V | |
| M | Output Voltage | Active State | 0 | V _{CC} | V | |
| V _{OUT} | Output Voltage | Three-State | 0 | 5.5 | V | |
| T _A | Operating Temperature | | -40 | +85 | °C | |
| | | V _{CC} at 1.8 V, 2.5 V ±0.2 V | 0 | 20 | K 1 | |
| t_r , t_f | Input Rise and Fall Times | V _{CC} at 3.3 V ±0.3 V | 0 | 10 | ns/V | |
| | | V _{CC} at 5.0 V ±0.5 V | 0 | 5 | | |
| | | SOT-23 | | 300 | | |
| 0 | The arrest Designation | SC70-5 | | 425 | °C/W | |
| θ_{JA} | Thermal Resistance | MicroPak-6 | | 500 | | |
| | | MicroPak2-6 | | 560 | | |

Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

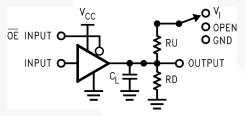
| Comple at | Danamatan | . , . | O a maliti a ma | T, | $T_A=+25$ °C | | | T _A =-40 to +85°C | |
|------------------|------------------------------|----------------------------|---|---------------------|--------------|---------------------|---------------------|------------------------------|-------|
| Symbol | mbol Parameter | V _{cc} Conditions | | Min. | Тур. | Max. | Min. | Max. | Units |
| ., | HIGH Level | 1.65 to 1.95 | | 0.75V _{CC} | | | 0.75V _{CC} | | ., |
| V_{IH} | Input Voltage | 2.30 to 5.50 | | 0.70V _{CC} | | | 0.70V _{CC} | | V |
| ., | LOW Level Input | 1.65 to 1.95 | | | | 0.25V _{CC} | | 0.25V _{CC} | ., |
| V_{IL} | Voltage | 2.30 to 5.50 | | | | 0.30V _{CC} | | 0.30V _{CC} | V |
| | | 1.65 | | 1.55 | 1.65 | | 1.55 | | |
| | | 1.80 | | 1.70 | 1.80 | | 1.70 | | |
| | | 2.30 | V _{IN} =V _{IH} , I _{OH} =-100 μA | 2.20 | 2.30 | | 2.20 | | V |
| | | 3.00 | | 2.90 | 3.00 | | 2.90 | | |
| 1/ | HIGH Level | 4.50 | | 4.40 | 4.50 | | 4.40 | | |
| V_{OH} | Output Voltage | 1.65 | I _{OH} =-4 mA | 1.29 | 1.52 | | 1.29 | | |
| | | 2.30 | I _{OH} =-8 mA | 1.90 | 2.15 | Á | 1.90 | | |
| | | 3.00 | I _{OH} =-16 mA | 2.40 | 2.80 | | 2.40 | | |
| | | 3.00 | I _{OH} =-24 mA | 2.30 | 2.68 | leg- | 2.30 | | |
| | | 4.50 | I _{OH} =-32 mA | 3.80 | 4.20 | | 3.80 | | |
| | 1.65 | | | 0.00 | 0.10 | | 0.00 | | |
| | | 1.80 | | | 0.00 | 0.10 | | 0.10 | |
| | | 2.30 | $V_{IN}=V_{IL}$, $I_{OL}=100 \mu A$ | | 0.00 | 0.10 | ¥! | 0.10 | |
| | 1/ | 3.00 | | | 0.00 | 0.10 | | 0.10 | |
| | LOW Level | 4.50 | | | 0.00 | 0.10 | | 0.10 | ., |
| V_{OL} | Output Voltage | 1.65 | I _{OL} =4 mA | | 0.80 | 0.24 | | 0.24 | V |
| | | 2.30 | I _{OL} =8 mA | | 0.10 | 0.30 | | 0.30 | |
| | | 3.00 | I _{OL} =16 mA | | 0.15 | 0.40 | | 0.40 | |
| | | 3.00 | I _{OL} =24 mA | | 0.22 | 0.55 | | 0.55 | |
| | | 4.50 | I _{OL} =32 mA | | 0.22 | 0.55 | | 0.55 | |
| I _{IN} | Input Leakage Current | 0 to 5.5 | 0 ≥ V _{IN} ≥ 5.5 V | | | ±1 | | ±10 | μΑ |
| l _{oz} | 3-STATE Output Leakage | 0 to 5.5 | $V_{IN}=V_{IH} \text{ or } V_{IL}$ $0 \ge V_O \ge 5.5 \text{ V}$ | | | ±1 | A | ±10 | μA |
| I _{OFF} | Power Off Leakage Current | 0 | V _{IN} or V _{OUT} =5.5 V | | | 1 | | 10 | μA |
| I _{cc} | Quiescent Supply Current | 1.65 to 5.50 | V _{IN} =5.5 V, GND | | | 2 | | 20 | μA |

AC Electrical Characteristics

| Compleal | Danamatan | Parameter V Condit | | T _A =+25°C | | T _A =-40 to +85°C | | Units | Ciaura | |
|------------------------------------|----------------------------|--------------------|---|-----------------------|------|------------------------------|------|-------|--------|----------|
| Symbol Parameter | | V _{cc} | Conditions | Min. | Тур. | Max. | Min. | Max. | Units | Figure |
| | | 1.65 | | 2.0 | 6.4 | 13.2 | 2.0 | 13.8 | | |
| | | 1.80 | C _L =15 pF, | 2.0 | 5.3 | 11.0 | 2.0 | 11.5 | | |
| | | 2.50 ±0.20 | $R_D=1 M\Omega$ | 8.0 | 3.4 | 7.5 | 0.8 | 8.0 | | |
| t _{PLH} ,t _{PHL} | Propagation Delay | 3.30 ±0.30 | S ₁ =OPEN | 0.5 | 2.5 | 5.2 | 0.5 | 5.5 | ns | Figure 4 |
| *FLN, *FNL | . ropaganon zonaj | 5.00 ±0.50 | | 0.5 | 2.1 | 4.5 | 0.5 | 4.8 | | Figure 6 |
| | | 3.30 ±0.30 | C _L =50 pF, | 1.5 | 3.2 | 5.7 | 1.5 | 6.0 | | |
| | | 5.00 ±0.50 | $R_D=500 \Omega$ $S_1=OPEN$ | 0.8 | 2.6 | 5.0 | 0.8 | 5.3 | | |
| | | 1.65 | $\begin{array}{c} \text{C}_\text{L} \! = \! 50 \text{ pF}, \\ \text{R}_\text{D} \! = \! 500 \ \Omega \\ \text{RU} \! = \! 500 \ \Omega \\ \text{S}_1 \! = \! \text{GND for } t_{\text{PZH}} \\ \text{S}_1 \! = \! V_{\text{IN}} \text{for } t_{\text{PZL}} \\ V_{\text{IN}} \! = \! 2 \text{-} V_{\text{CC}} \end{array}$ | 2.0 | 8.4 | 15.0 | 2.0 | 15.6 | ns | |
| | | 1.80 | | 2.0 | 7.0 | 12.5 | 2.0 | 13.0 | | |
| $t_{PZL,}t_{PZH}$ | Output Enable Time | 2.50 ±0.20 | | 1.5 | 4.6 | 8.5 | 1.5 | 9.0 | | |
| | | 3.30 ±0.30 | | 1.5 | 3.5 | 6.2 | 1.5 | 6.5 | | |
| | | 5.00 ±0.50 | | 0.8 | 2.8 | 5.5 | 0.8 | 5.8 | | Figure 4 |
| | | 1.65 | C _L =50 pF, | 2.0 | 6.5 | 13.2 | 2.0 | 14.5 | 115 | Figure 6 |
| | | 1.80 | R _D =500 Ω | 2.0 | 5.4 | 11.0 | 2.0 | 12.0 | | |
| $t_{PLZ,}t_{PHZ}$ | Output Disable Time | 2.50 ±0.20 | RU=500 Ω S ₁ =GND for t _{PHZ} | 1.5 | 3.5 | 8.0 | 1.5 | 8.5 | | |
| | | 3.30 ±0.30 | $S_1 = V_{IN}$ for t_{PLZ} | 1.0 | 2.8 | 5.7 | 1.0 | 6.0 | | |
| | | | V _{IN} =2•V _{CC} | 0.5 | 2.1 | 4.7 | 0.5 | 5.0 | | |
| C _{IN} | Input Capacitance | 0.00 | | | 4 | | | | pF | |
| C_OUT | Output Capacitance | 0.00 | | | 8 | | | | | |
| <u></u> | Power Dissipation | 3.30 | | | 17 | | | | , F | |
| C _{PD} | Capacitance ⁽²⁾ | 5.00 | | | 24 | | | | pF | Figure 5 |

Note:

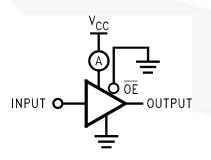
2. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output lading and operating at 50% duty cycle. C_{PD} is related to I_{CCD} dynamic operating current by the expression: I_{CCD}=(C_{PD})(V_{CC})(f_{IN})+(I_{CC}static).



Note:

3. C_L includes load and stray capacitance. Input PRR=1.0 MHz, t_W =500 ns.

Figure 4. AC Test Circuit



Note:

 Input=AC Waveform; t_r=t_f=1.8 ns; PRR=10 MHz; Duty Cycle=50%.

Figure 5. I_{CCD} Test Circuit

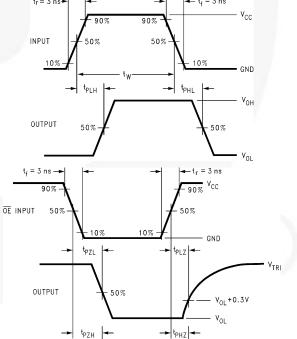


Figure 6. AC Waveforms

OUTPUT

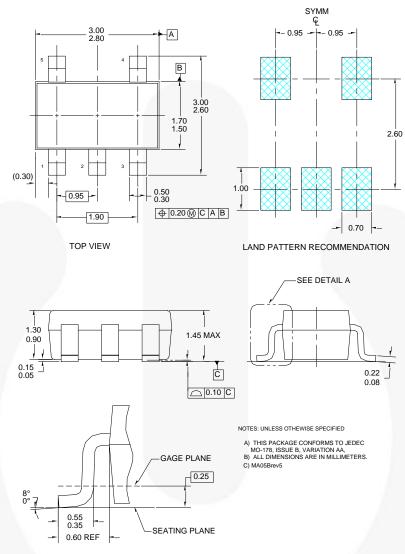


Figure 7. 5-Lead SOT23, JEDEC MO-178 1.6 mm

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Tape and Reel Specifications

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: http://www.fairchildsemi.com/packaging/SOT23-5L_tr.pdf.

| Package Designator Tape Section | | Cavity Number | Cavity Status | Cover Type Status |
|---------------------------------|--------------------|---------------|---------------|-------------------|
| | Leader (Start End) | 125 (Typical) | Empty | Sealed |
| M5X | Carrier | 3000 | Filled | Sealed |
| | Trailer (Hub End) | 75 (Typical) | Empty | Sealed |

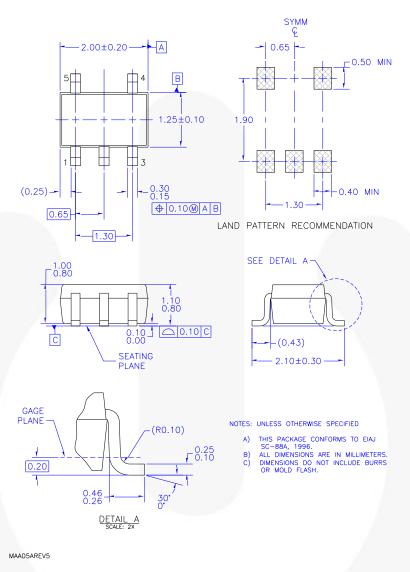


Figure 8. 5-Lead, SC70, EIAJ SC-88a, 1.25 mm Wide

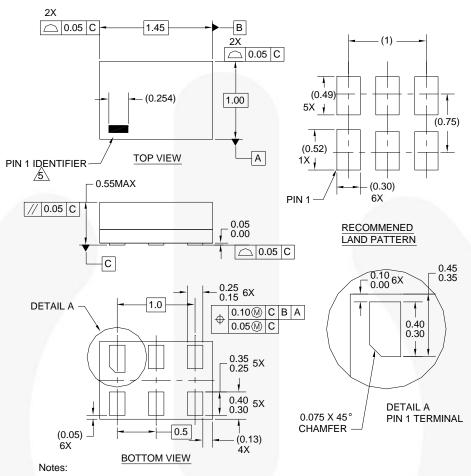
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Tape and Reel Specifications

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| Package Designator | Tape Section | Cavity Number | Cavity Status | Cover Type Status |
|--------------------|--------------------|----------------------|---------------|-------------------|
| | Leader (Start End) | | Empty | Sealed |
| P5X | Carrier | 3000 | Filled | Sealed |
| | Trailer (Hub End) | 75 (Typical) | Empty | Sealed |



- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994
- 4. FILENAME AND REVISION: MAC06AREV4
- 5. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY

OTHER LINE IN THE MARK CODE LAYOUT.

Figure 9. 6-Lead, MicroPak™, 1.0 mm Wide

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| Package Designator | Tape Section | Cavity Number | Cavity Status | Cover Type Status | |
|--------------------|--------------------|---------------|---------------|-------------------|--|
| | Leader (Start End) | | Empty | Sealed | |
| L6X | Carrier | 5000 | Filled | Sealed | |
| | Trailer (Hub End) | 75 (Typical) | Empty | Sealed | |

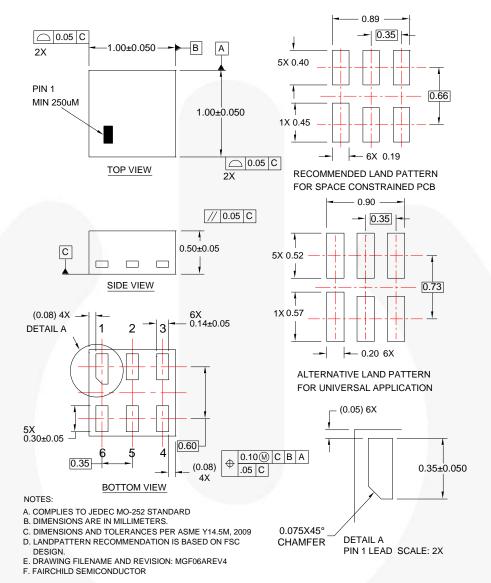


Figure 10. 6-Lead, MicroPak2, 1x1 mm Body, .35 mm Pitch

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Tape and Reel Specifications

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| Package Designator Tape Sect | | Cavity Number | Cavity Status | Cover Type Status |
|------------------------------|--------------------|---------------|---------------|-------------------|
| | Leader (Start End) | 125 (Typical) | Empty | Sealed |
| FHX | Carrier | 5000 | Filled | Sealed |
| | Trailer (Hub End) | 75 (Typical) | Empty | Sealed |





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